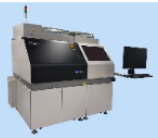
Micro Crack

Purpose	Field proven optical solution provides ultra thin micro crack defect detection capability on Silicon bare die and Integrated Passive Devices (IPD).
Technology	1. **Ultimate PVI** – Inspects 0.5um micro crack on wide range of package types and sizes range from 2 x 2 mm to 120 x 120 mm (130 x150 mm for tScan)

STI Products	Ultimate PVI
 **Hexa – Tray 2D & 3D Scan**	✓
 **tScan – 2D & 3D High Speed Scan-Pack**	✓